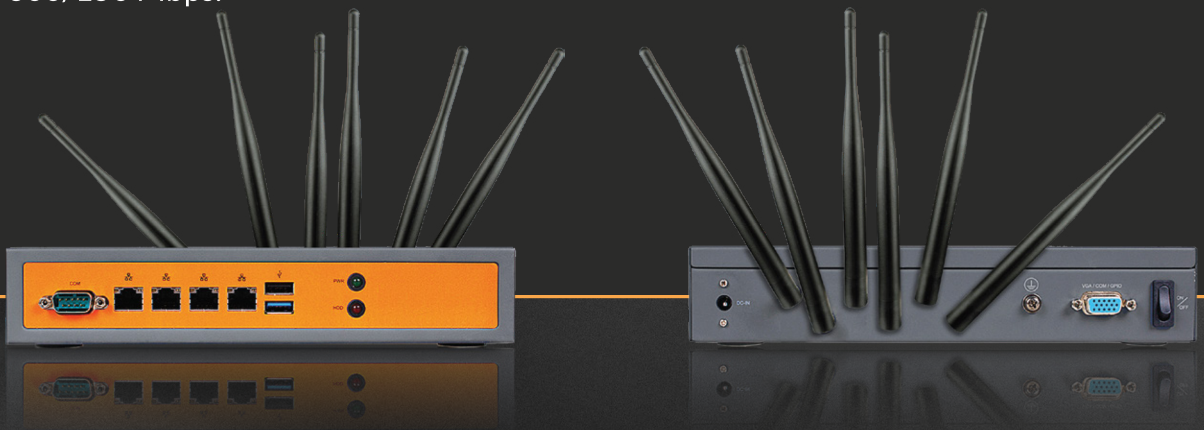
NXT BOND

This device aggregates multiple uplinks into a single pipe and allows for seamless failover from a wired to wireless network. It has 3xLTE cat 6/11 modems with global-band support, and aggregated speeds of up to 600/150 Mbps.



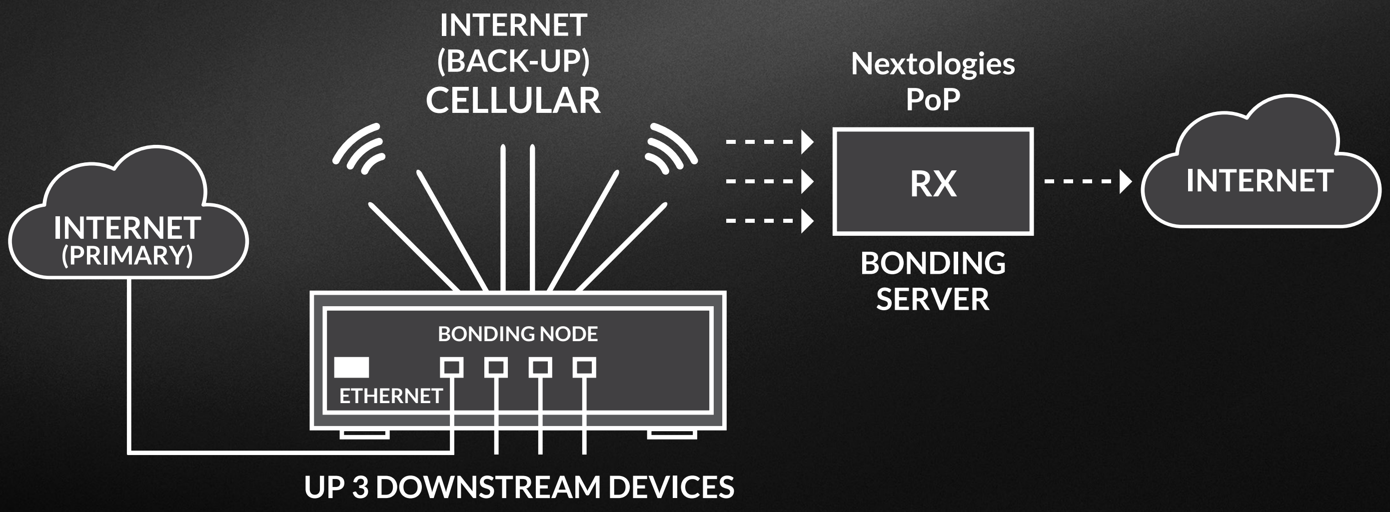
SPECIFICATIONS NXT BOND3-m1 CELLULAR BONDING DEVICE

Motherboard Specification

CPU	Intel® Celeron J1900, 2.0GHz Quad-Core SoC, 10W, Bay Trail

Chassis Specification

Product size	232 (W) * 152 (D) * 44 (H) mm
Environment	Operating Temperature : 0 ~ 50°C Storage Temperature : -10 ~ 70°C
Standard Accessory	√ 60W AC-DC Adapter x1 √ Power Cord x1
Functional	Networking Appliance, Firewall/Router, Industrial Contol, Digital Security, IoT SystemCE,FCC,ErP For Barebone
Certificate	CE, FCC, TUV, UL, CCC, CB, ErP For Power Adapter



INTERNET (BACK-UP) CELLULAR

Nextologies PoP

INTERNET (PRIMARY)

RX

BONDING SERVER

INTERNET

BONDING NODE

ETHERNET

UP 3 DOWNSTREAM DEVICES

NEXTOLOGIES

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